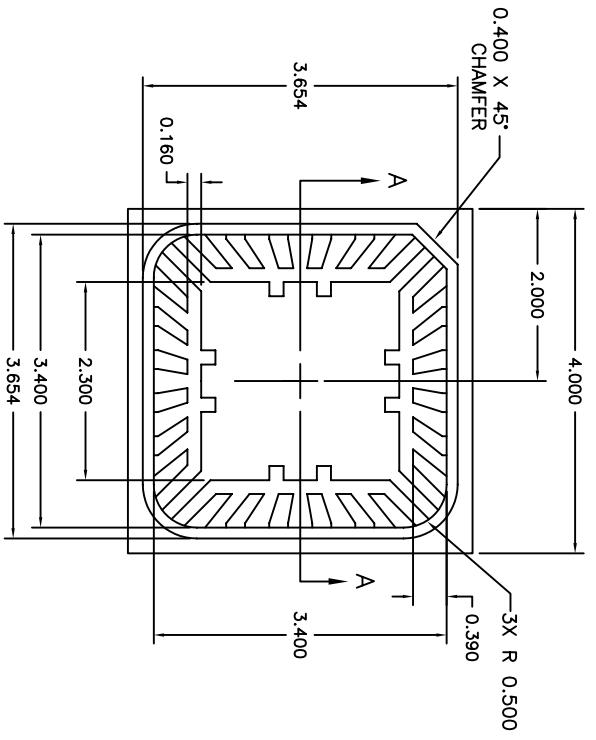


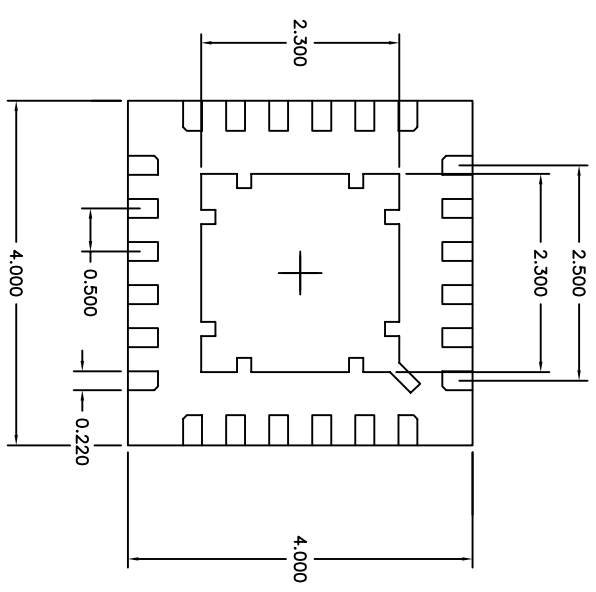
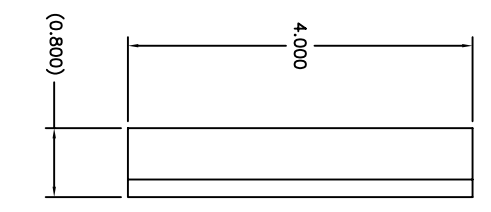
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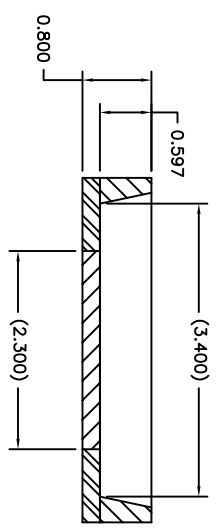
REVISIONS			APPROVED
ECON NO.	DATE	DESCRIPTION	D.BENAVANDO
10498	10/25/05	PRODUCTION RELEASE	



TOP VIEW



BOTTOM VIEW



SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 2. LEAD FRAME: COPPER, 194 FH.
 3. LEAD FINISH: FULL GOLD PLATE.
 4. FRAME THICKNESS: 0.2030 ± 0.0076.
 5. DIE PAD: 2.300mm X 2.300mm.
 6. JEDEC OUTLINE: MO-220 (VGGD-2)



UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS

TOLERANCES ARE: X.XXX ± 0.015 X.XXXX ± 0.0050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	W. GRIFFITTS	DATE	10/25/05
APP BY	P. FLASKERUD	DATE	10/25/05
CUSTOMER	---		

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SEMPAC, INC.
 Open-Pak™ Technologies
 www.sempac.com
 588 E. WEDDELL DRIVE, SUITE 5
 SUNNYVALE, CALIFORNIA 94089
 PHONE: (408) 400-9002 FAX: (408) 400-9006

24 Lead 4mm x 4mm
 MLP Open_pak

SIZE	PART NO.	REV
A	MLP4X4-24-OP-01	2
SCALE NONE	CAD FILE	SHEET 1 OF 1
	MLP4X4-24-OP-01-R2.DWG	

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